

BR2N7002K2Q
Rev.C Jul.-2022

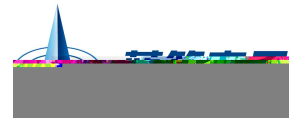


DATA SHEET

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/ Descriptions

SOT-23 | } } ~ N € , MOS f , Z ...z
N-CHANNEL MOSFET in a SOT-23 Plastic Package.

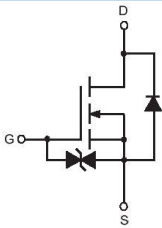
/ Features

† ‡ † ^ ! T %\$ < € ' ' " i " u < € z • < - — ~ 2KV7 b c AEC-Q101 d e H f g h i j 7 ™
§] ^ z
Sensitive gate trigger current and Low Holding current.ESD protected up to 2KV, Qualified to AEC-Q101 Standards for High Reliability, HF Product.

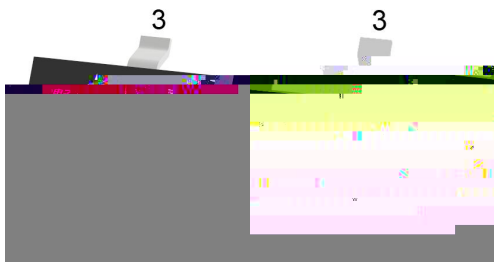
/ Applications

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Intended for use in general purpose switching and phase control applications, Meet the stringent requirements of automotive applications.

/ Equivalent Circuit



/ Pinning



PIN 1y G

PIN 2y S

PIN 3y D

/ Marking

Marking	702Q2
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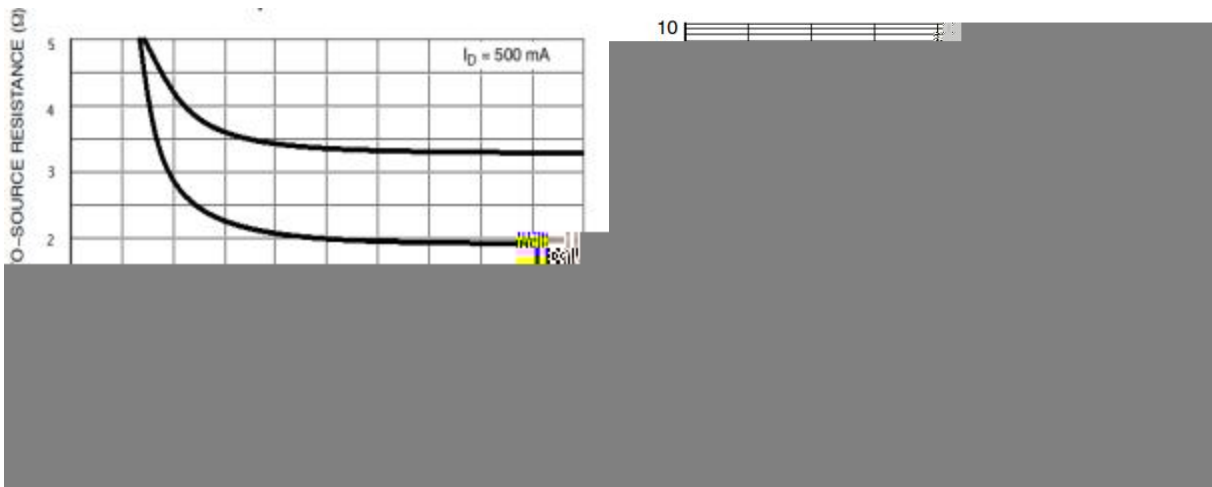
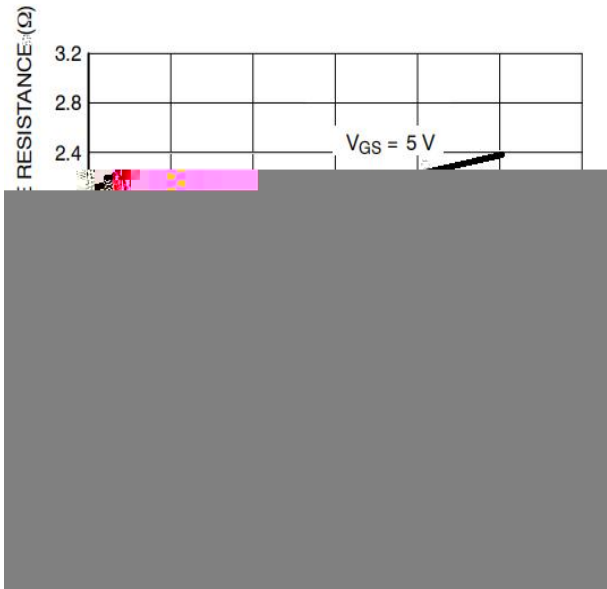
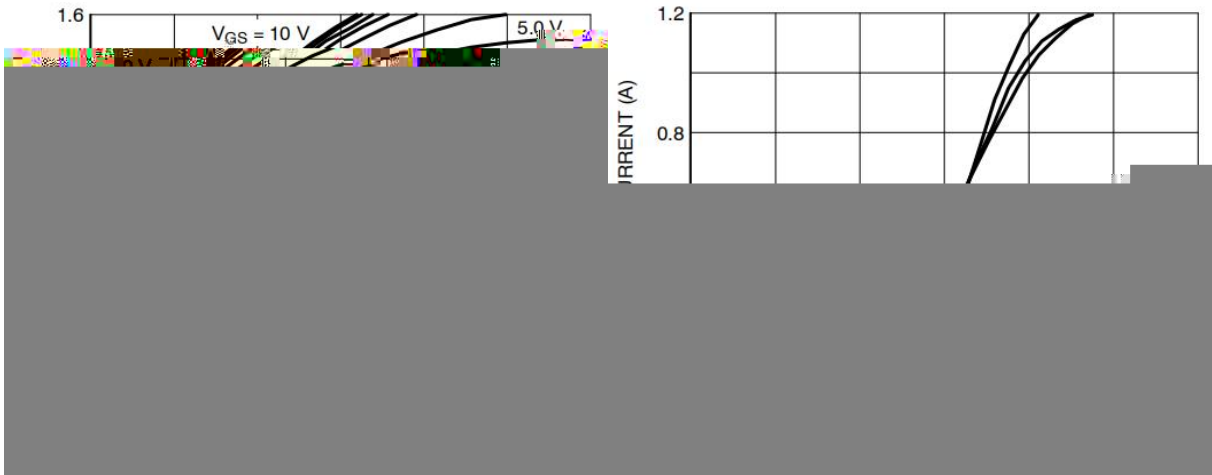
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Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Turn-On Delay Time	$t_{d(ON)}$			12.2		
Rise Time	t	VGS =10V, VDD=25V, ID=500mA, RG=25 Ω				ns

/ Electrical Characteristic Curve



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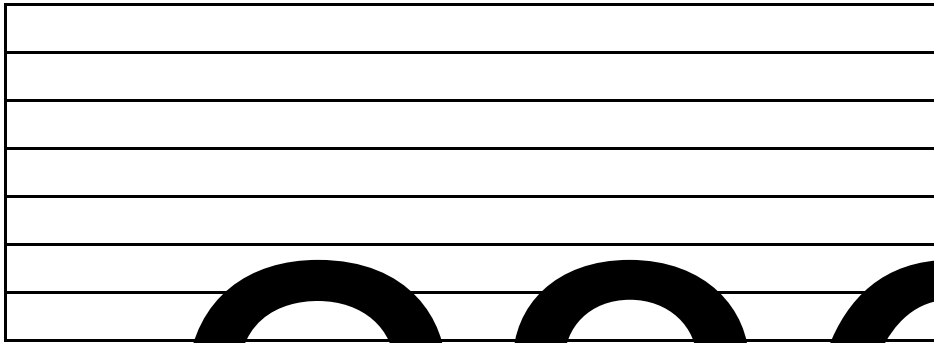
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() / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150~200 ，时间 60~120sec; 1.Pre heating:150~200 ，Time:60~120sec.
- 2、峰值温度 255 ± 5 ，时间持续 5~0.5sec; 2.Peak Temp.:255 ± 5 ，Duration:5~0.5sec.
- 3、焊接制程冷却速度为 2~5 /sec. 3.Cooling Speed:2~5 /sec.

/ Resistance to Soldering Heat Test Conditions

温度：260 ± 5